



Description

The XR46000 is a silicon N-channel enhanced power MOSFET. With low conduction loss, good switching performance and high avalanche energy, it is suitable for various power supply system, especially for AC step driving application for LED lighting.

The package type is SOT-223, which comply with the RoHS standard.

Key Parameters

V_{DS}	600V
I_D	1.5A
P_D ($T_C = 25^\circ\text{C}$)	20W
$R_{DS,ON,typ}$	7.0 Ω

FEATURES

- Fast switching
- ESD improved capability
- Low gate charge (Typ. 7.5nC)
- Low reverse transfer capacitance (Typ. 5.0pF)

APPLICATIONS

- LED lighting applications
 - Downlight
 - High bay
 - Specialty
 - Architectural

Equivalent Circuit

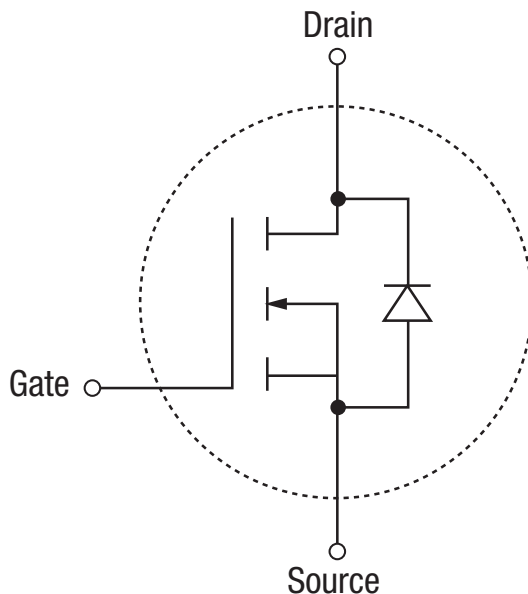
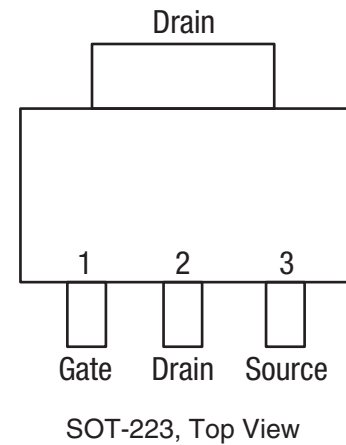


Figure 1. Equivalent Circuit

Pin Configuration



Absolute Maximum Ratings

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

$T_C = 25^\circ\text{C}$ unless otherwise noted.

V_{DSS} drain-to-source voltage 600V

I_D continuous drain current ($T_C = 25^\circ\text{C}$) 1.5A

I_D continuous drain current ($T_C = 100^\circ\text{C}$) 0.85A

I_{DM} pulsed drain current 6A

V_{GS} gate-to-source voltage $\pm 30\text{V}$

P_D power dissipation ($T_C = 25^\circ\text{C}$) 20W

P_D derating factor above 25°C $0.16\text{W}/^\circ\text{C}$

$T_{STORAGE}$ storage temperature range -65°C to 150°C

E_{AS} single pulse avalanche energy 80mJ

NOTE:

Unless otherwise noted, all tests are pulsed tests at the specified temperature, therefore: $T_J = T_C = T_A$.

Operating Conditions

T_J operating junction temperature 150°C

T_A operating ambient temperature -40°C to 85°C

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF Characteristic						
BV _{DSS}	Drain to source breakdown voltage	V _{GS} = 0V, I _D = 250μA	600			V
ΔBV _{DSS} /ΔT _J	Breakdown voltage temperature coefficient	I _D = 250μA, reference 25°C		0.71		V/°C
I _{DSS}	Drain to source leakage current	V _{DS} = 600V, V _{GS} = 0V, T _A = 25°C			25	μA
		V _{DS} = 600V, V _{GS} = 0V, T _A = 125°C			250	
I _{GSS(F)}	Gate to source forward leakage	V _{GS} = 30V			12	μA
I _{GSS(R)}	Gate to source reverse leakage	V _{GS} = -28V			-12	
ON Characteristic (pulse width tp ≤ 380μs, δ ≤ 2%)						
R _{DS(ON)}	Drain to source on-resistance	V _{GS} = 10V, I _D = 0.75A		7.0	8.0	Ω
V _{GS(TH)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0		4.0	V
Dynamic Characteristic						
g _{fs}	Forward transconductance	V _{DS} = 15V, I _D = 0.75A		1.0		s
C _{iSS}	Input capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		170		pF
C _{oss}	Output capacitance			27		
C _{rSS}	Reverse transfer capacitance			5		
Resistive Switching Characteristic						
t _{d(ON)}	Turn-on delay time	I _D = 1.5A, V _{DD} = 300V, V _{GS} = 10V, R _G = 4.7Ω		8		ns
t _r	Rise time			30		
t _{d(OFF)}	Turn-off delay time			22		
t _f	Fall time			55		
Q _g	Total gate charge	I _D = 1.5A, V _{DD} = 480V, V _{GS} = 10V		7.5		nC
Q _{gs}	Gate to source charge			1.7		
Q _{gd}	Gate to drain “Miller” charge			4.0		
Source-Drain Diode Characteristics (pulse width tp ≤ 380us, δ ≤ 2%)						
I _S	Continuous source current (body diode)				1.5	A
I _{SM}	Maximun source current (body diode)				6.0	
V _{SD}	Diode forward voltage	I _S = 1.5A, V _{GS} =0V			1.5	V
T _{rr}	Reverse recovery time	I _D = 1.5A, T _J = 25°C, dI _F /dt = 100A/μs, V _{GS} = 0V		530		ns
Q _{rr}	Reverse recovery charge			1100		nC
I _{RRM}	Reverse recovery current			4.4		A

Typical Performance Characteristics

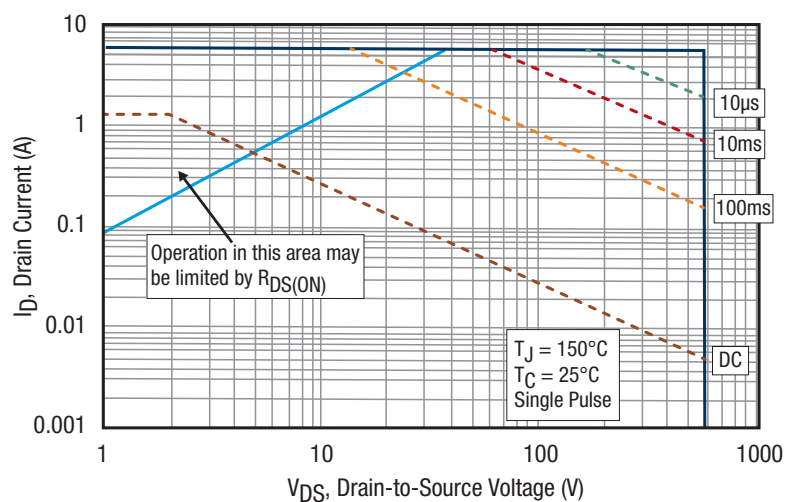


Figure 2. Safe Operating Area

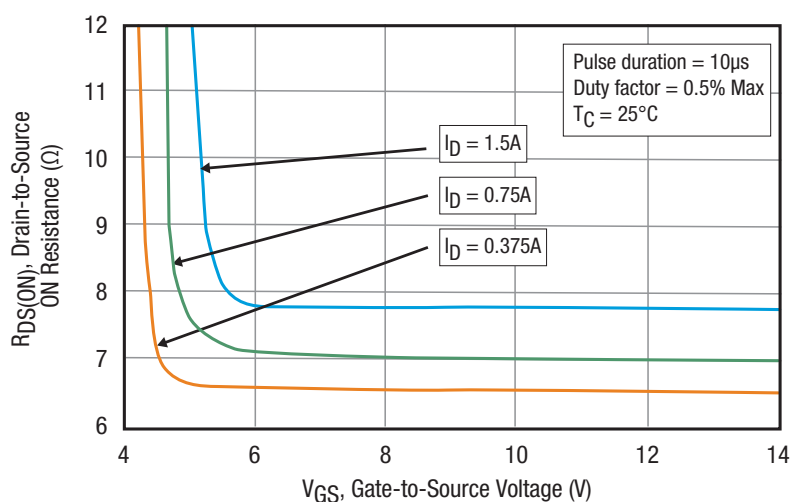


Figure 3. Typical Drain-to-Source ON Resistance vs. Gate Voltage and Drain Current

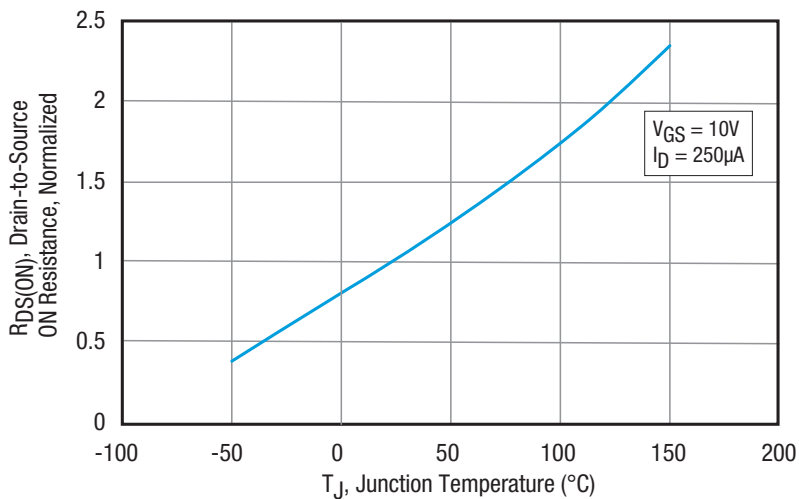
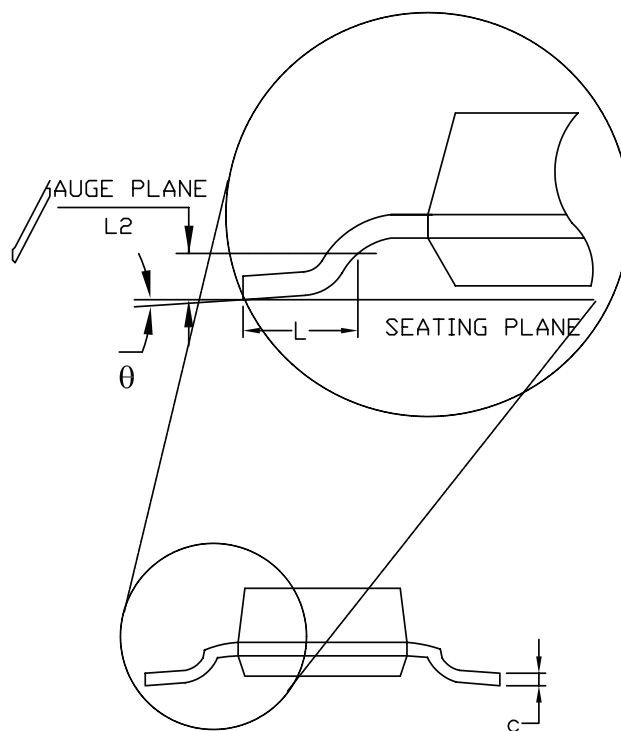
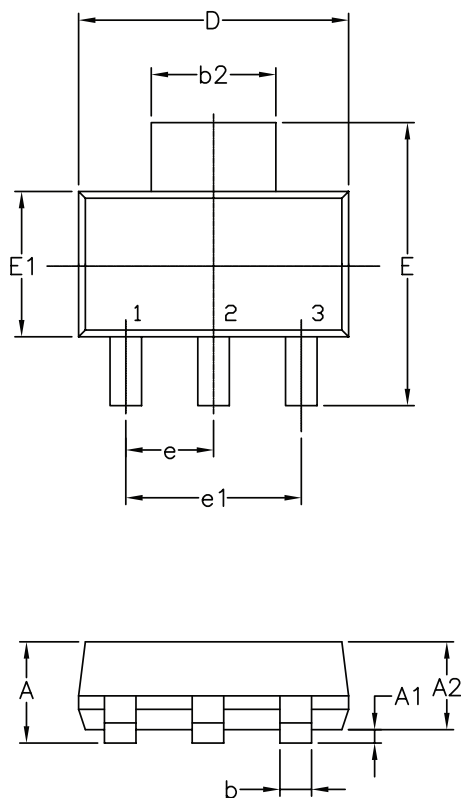


Figure 4. Typical Drain-to-Source ON Resistance vs. Junction Temperature

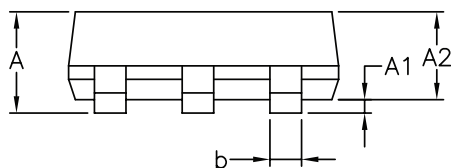
Package Description

Top View



Front View

Side View



3 Pin SOT-223 JEDEC TO-261 Variation AA						
SYMBOLS	DIMENSIONS IN MM (Control Unit)			DIMENSIONS IN INCH (Reference Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	1.80	—	—	0.071
A1	0.02	—	0.10	0.001	—	0.004
A2	1.50	1.60	1.70	0.060	0.063	0.067
b	0.66	0.76	0.84	0.026	0.030	0.033
b2	2.90	3.00	3.10	0.114	0.118	0.122
c	0.23	0.30	0.35	0.010	0.012	0.014
D	6.30	6.50	6.70	0.248	0.256	0.264
E	6.70	7.00	7.30	0.264	0.276	0.287
E1	3.30	3.50	3.70	0.130	0.138	0.146
e	2.30 BSC			0.091 BSC		
e1	4.60 BSC			0.182 BSC		
L	0.75	—	—	0.030	—	—
L2	0.25 BSC			0.010 BSC		
θ	0°	—	10°	0°	—	10°
N	3			3		

Ordering Information

Part Number	Operating Temperature Range	Environmental Rating	Package	Packaging Method
XR46000ESE	$-40^{\circ}\text{C} \leq T_J \leq 150^{\circ}\text{C}$	RoHS compliant and Green ⁽¹⁾	SOT-223	Bulk
XR46000ESETR			SOT-223	Tape and reel
XR46000ECF			Dice	Wafer

NOTE:

1. Visit www.exar.com for more information.

Revision History

Revision	Date	Description
1A	Aug 2016	Initial release



www.exar.com

48760 Kato Road
Fremont, CA 94538
USA

Tel.: +1 (510) 668-7000
Fax: +1 (510) 668-7001
Email: LEDtechsupport@exar.com

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